



N-Channel Enhancement Mode MOSFET

GENERAL DESCRIPTION

The SI2302 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

FEATURES

$V_{DS} = 20V$ $I_D = 2.3A$

$R_{DS(ON)} < 75m\Omega$ @ $V_{GS}=4.5V$

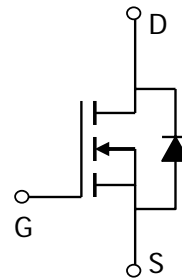
Available in a 3-Pin SOT23-3 Package

Application

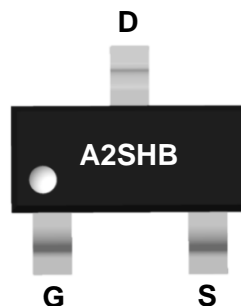
Battery protection

Load switch

Uninterruptible power supply



SOT-23-3L
(TOP VIEW)



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain current-continuous ^{note1} @ $T_J=125^\circ\text{C}$	I_D	2.3	A
-pulse d ^{note2}	I_{DM}	8	A
Drain-source Diode forward current	I_S	2	A
maximum Power Dissipation	P_D	1.25	W
Operating Junction Temperature Range	T_J	-55 To 150	$^\circ\text{C}$
Thermal Resistance Junction-to ambient	$R_{th JA}$	100	$^\circ\text{C/W}$

Note :

- 1、 surface mounted on FR4 board, $t \leq 10\text{sec}$
- 2、 pulse test: pulse width $\leq 300\mu\text{s}$, duty $\leq 2\%$



ELECTRICAL CHARACTERISTICS

(TA = 25°C, unless otherwise noted.)

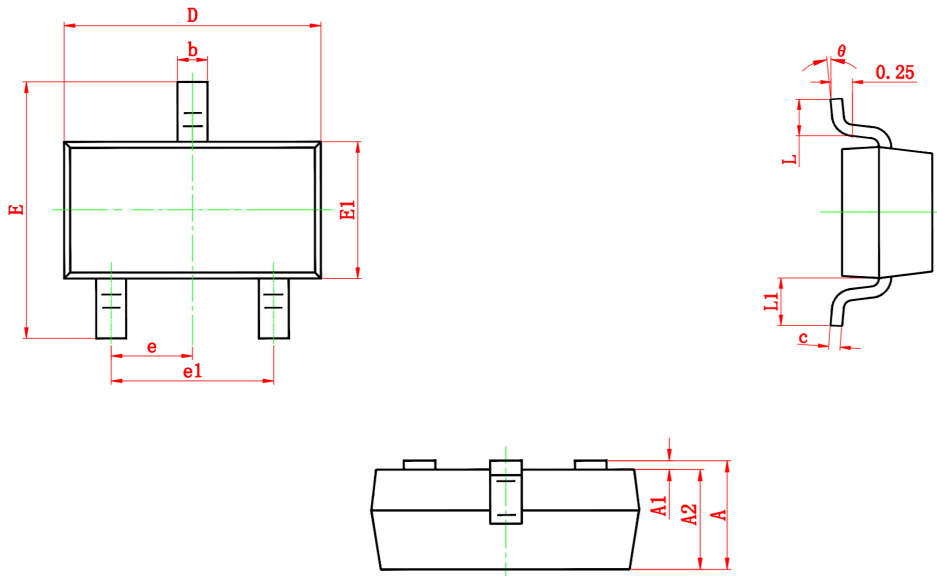
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage	I _{GSS}	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.75	1.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =2A	-	55	75	mΩ
		V _{GS} =2.5V, I _D =1A		68	90	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =2A	-	5	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{ISS}	V _{DS} =10V,V _{GS} =0V, F=1.0MHz	-	180	-	PF
Output Capacitance	C _{OSS}		-	38	-	PF
Reverse Transfer Capacitance	C _{rss}		-	20	-	PF
Switching Characteristics						
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V,RL=3Ω V _{GS} =4.5V,R _{GEN} =6Ω	-	8	-	nS
Turn-on Rise Time	t _r		-	7	-	nS
Turn-Off Delay Time	t _{d(off)}		-	30	-	nS
Turn-Off Fall Time	t _f		-	7	-	nS
Total Gate Charge	Q _g	V _{DS} =10V,I _D =3A, V _{GS} =4.5V	-	3.5	-	nC
Gate-Source Charge	Q _{gs}		-	0.6	-	nC
Gate-Drain Charge	Q _{gd}		-	0.45	-	nC
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =3A	-	0.76	1.16	V

Note :

- 1、 guaranteed by design, not subject to production testing



PACKAGE DESCRIPTION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
θ	0°	8°	0°	8°

Notes

1. All dimensions are in millimeters.
2. Tolerance $\pm 0.10\text{mm}$ (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.